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TECHNICAL REPORT





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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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OPTICAL AMPLIFIERS -

Part 9: Semiconductor optical amplifiers (SOAs)

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IEC/TR 61292-9, which is a technical report, has been prepared by subcommittee 86C: Fibre optic systems and active devices, of IEC technical committee 86: Fibre optics.

The text of this technical report is based on the following documents:

Enquiry draft	Report on voting
86C/1148/DTR	86C/1183/RVC

Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61292 series, published under the general title *Optical amplifiers*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

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INTRODUCTION

Optical amplifiers (OAs) are necessary components as booster, line and pre-amplifiers for current optical network systems. IEC TC86/SC86C, has published many standards for OAs and most of them are focused on optical fibre amplifiers (OFAs), which are commonly deployed in commercial optical network systems. Recently, semiconductor optical amplifiers (SOAs) have attracted attention for applications in gigabit passive optical network (GPON) and 100 Gbit Ethernet (GbE) systems. This is because SOA chips are as small as laser diodes (LDs) and only require an electrical current.

Although SOAs for the 1 310 nm or 1 550 nm bands have been extensively studied since the 1980s, the use of SOAs is still limited to laboratories or field trials. This is due to specific performance features of SOAs such as gain ripple and polarization dependent gain (PDG). Thus, there are very few IEC standards addressing SOAs. One example is IEC/TR 61292-3, which is a technical report for classification, characteristics and applications of OAs including SOAs. However, it only deals with general information on SOAs and does not contain the detail information on test methods that are necessary to measure precisely the particular parameters of SOAs.

This technical report provides a better understanding of specific features of SOAs as well as information on measuring gain and PDG. It is anticipated that future standards will address performance and test methodology.

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OPTICAL AMPLIFIERS -

Part 9: Semiconductor optical amplifiers (SOAs)

1 Scope

IEC/TR 61292-9, which is a technical report, focuses on SOAs, especially the specific features and measurement of gain and PDG.

In this report, only the amplifying application of SOAs is described.

Other applications, such as modulation, switching and non-linear functions, are not covered.

Potential applications of SOAs, however, such as reflective SOAs (RSOAs) for the seeded wavelength division multiplexing passive optical network (WDM-PON), are briefly reviewed in Annex A.

2 Terms, definitions, abbreviations and symbols

2.1 Terms and definitions

For the purposes of this document, the following terms, definitions, abbreviations and symbols apply.

2.1.1

SOA

generic term that includes the "SOA chip" and the "SOA module"

2.1.2

SOA chip

semiconductor chip which is the active component of the SOA module

2.1.3

SOA module

fibre-pigtailed optical component that consists of the SOA chip, lenses, optical isolators (if necessary), a thermoelectric cooler (TEC), a thermistor, a package and fibres

2.2 Abbreviations

AR anti-reflection

ASE amplified spontaneous emission

BPF band pass filter

CFP 100 Gbit form-factor pluggable

CW continuous wave DEMUX demultiplexer

DFB distributed feedback

EDFA erbium-doped fibre amplifier

FWM four-wave mixing GbE gigabit Ethernet

GPON gigabit capable passive optical network

LD laser diode

MSA multi-source agreement
MMI multi-mode interference
MQWs multiple quantum wells

NF noise figure
OA optical amplifier
OFA optical fibre amplifier
OLT optical line termination
ONU optical network unit
OPM optical power meter
PC polarization controller

PD photodiode

PDCE polarization dependence of coupling efficiency

PDG polarization dependent gain PIC photonic integrated circuit

POL polarizer

PON passive optical network

RSOA reflective semiconductor optical amplifier

SLD superluminescent diode
SMF single mode fibre

SOA semiconductor optical amplifier

TE transverse electric

TEC thermoelectric cooler (

TIA transimpedance amplifier 292-9:201

TM dards transverse magnetic

VOA variable optical attenuator

WDM wavelength division multiplexing

XGM cross gain modulation
XPM cross phase modulation

2.3 Symbols

G optical gain I_{F} forward current

 T_{TE} TE mode confinement factor T_{TM} TM mode confinement factor

L chip length

 $n_{\rm eff}$ effective refractive index

NF noise figure

 $n_{\rm sp}$ spontaneous emission factor

 λ wavelength

 $\Delta \lambda_{\text{ripple}}$ period of gain ripple

 $\begin{array}{ll} \textit{PDCE} & \text{polarization dependence of coupling efficiency} \\ \textit{PDG}_{\text{active}} & \text{polarization dependence of active layer gain} \\ \textit{PDG}_{\text{total}} & \text{total polarization dependence of single pass gain} \end{array}$